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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	3424
Number of Logic Elements/Cells	30816
Total RAM Bits	2506752
Number of I/O	556
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FCBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp30-6ff896c

Virtex-II Pro / Virtex-II Pro X Device/Package Combinations and Maximum I/Os

Offerings include ball grid array (BGA) packages with 1.0 mm pitch. In addition to traditional wire-bond interconnect (FG/FGG packages), flip-chip interconnect (FF packages) is used in some of the BGA offerings. Flip-chip interconnect construction supports more I/Os than are possible in wire-bond versions of similar packages, providing a high pin count and excellent power dissipation.

The device/package combination table (Table 3) details the maximum number of user I/Os and RocketIO / RocketIO X MGTs for each device and package using wire-bond or flip-chip technology.

The FF1148 and FF1696 packages have no RocketIO transceivers bonded out. Extra SelectIO-Ultra resources occupy available pins in these packages, resulting in a higher user I/O count. These packages are available for the XC2VP40, XC2VP50, and XC2VP100 devices only.

The I/Os per package count includes all user I/Os except the 15 control pins (CCLK, DONE, M0, M1, M2, PROG_B, PWRDWN_B, TCK, TDI, TDO, TMS, HSWAP_EN, DXN, DXP, and RSVD), VBATT, and the RocketIO / RocketIO X transceiver pins.

Table 3: Virtex-II Pro Device/Package Combinations and Maximum Number of Available I/Os

Package ⁽¹⁾	FG256/ FGG256	FG456/ FGG456	FG676	FF672	FF896	FF1152	FF1148	FF1517	FF1704	FF1696
Pitch (mm)	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00	1.00
Size (mm)	17 x 17	23 x 23	26 x 26	27 x 27	31 x 31	35 x 35	35 x 35	40 x 40	42.5 x 42.5	42.5 x 42.5
XC2VP2	140 / 4	156 / 4		204 / 4						
XC2VP4	140 / 4	248 / 4		348 / 4						
XC2VP7		248 / 8		396 / 8	396 / 8					
XC2VP20			404 / 8		556 / 8	564 / 8				
XC2VPX20					552 / 8 ⁽²⁾					
XC2VP30			416 / 8		556 / 8	644 / 8				
XC2VP40			416 / 8			692 / 12	804 / 0 ⁽³⁾			
XC2VP50						692 / 16	812 / 0 ⁽³⁾	852 / 16		
XC2VP70								964 / 16	996 / 20	
XC2VPX70									992 / 20 ⁽²⁾	
XC2VP100									1,040 / 20	1,164 / 0 ⁽³⁾

Notes:

- Wirebond packages FG256, FG456, and FG676 are also available in Pb-free versions FGG256, FGG456, and FGG676. See [Virtex-II Pro Ordering Examples](#) for details on how to order.
- Virtex-II Pro X device is equipped with RocketIO X transceiver cores.
- The RocketIO transceivers in devices in the FF1148 and FF1696 packages are not bonded out to the package pins.

Maximum Performance

Maximum performance of the RocketIO / RocketIO X transceiver and the PowerPC processor block varies, depending on package style and speed grade. See Table 4 for details. [Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics](#) contains the rest of the FPGA fabric performance parameters.

Table 4: Maximum RocketIO / RocketIO X Transceiver and Processor Block Performance

Device	Speed Grade			Units
	-7 ⁽¹⁾	-6	-5	
RocketIO X Transceiver FlipChip (FF)	N/A	6.25 ⁽³⁾	4.25 ⁽³⁾	Gb/s
RocketIO Transceiver FlipChip (FF)	3.125	3.125	2.0	Gb/s
RocketIO Transceiver Wirebond (FG)	2.5	2.5	2.0	Gb/s
PowerPC Processor Block	400 ⁽²⁾	350 ⁽²⁾	300	MHz

Notes:

- 7 speed grade devices are not available in Industrial grade.
- IMPORTANT!** When CPMC405CLOCK runs at speeds greater than 350 MHz in -7 Commercial grade dual-processor devices, or greater than 300 MHz in -6 Industrial grade dual-processor devices, users must implement the technology presented in [XAPP755](#), "PowerPC 405 Clock Macro for -7(C) and -6(I) Speed Grade Dual-Processor Devices." Refer to Table 1 to identify dual-processor devices.
- XC2VPX70 is only available at fixed 4.25 Gb/s baud rate.

- Single-cycle and multi-cycle mode option for I-side and D-side interfaces
- Single cycle = one CPU clock cycle;
multi-cycle = minimum of two and maximum of eight CPU clock cycles
- FPGA configurable DCR addresses within DSOCM and ISOCM.
- Independent 16 MB logical memory space available within PPC405 memory map for each of the DSOCM and ISOCM. The number of block RAMs in the device might limit the maximum amount of OCM supported.
- Maximum of 64K and 128K bytes addressable from DSOCM and ISOCM interfaces, respectively, using address outputs from OCM directly without additional decoding logic.

Data-Side OCM (DSOCM)

- 32-bit Data Read bus and 32-bit Data Write bus
- Byte write access to DSBRAM support
- Second port of dual port DSBRAM is available to read/write from an FPGA interface
- 22-bit address to DSBRAM port
- 8-bit DCR Registers: DSCNTL, DSARC
- Three alternatives to write into DSBRAM: BRAM initialization, CPU, FPGA H/W using second port

Instruction-Side OCM (ISOCM)

The ISOCM interface contains a 64-bit read only port, for instruction fetches, and a 32-bit write only port, to initialize or test the ISBRAM. When implementing the read only port, the user must deassert the write port inputs. The preferred method of initializing the ISBRAM is through the configuration bitstream.

- 64-bit Data Read Only bus (two instructions per cycle)
- 32-bit Data Write Only bus (through DCR)
- Separate 21-bit address to ISBRAM
- 8-bit DCR Registers: ISCNTL, ISARC
- 32-bit DCR Registers: ISINIT, ISFILL
- Two alternatives to write into ISBRAM: BRAM initialization, DCR and write instruction

Clock/Control Interface Logic

The clock/control interface logic provides proper initialization and connections for PPC405 clock/power management, resets, PLB cycle control, and OCM interfaces. It also couples user signals between the FPGA fabric and the embedded PPC405 CPU core.

The processor clock connectivity is similar to CLB clock pins. It can connect either to global clock nets or general routing resources. Therefore the processor clock source can come from DCM, CLB, or user package pin.

CPU-FPGA Interfaces

All Processor Block user pins link up with the general FPGA routing resources through the CPU-FPGA interface. Therefore processor signals have the same routability as other

non-Processor Block user signals. Longlines and hex lines travel across the Processor Block both vertically and horizontally, allowing signals to route through the Processor Block.

Processor Local Bus (PLB) Interfaces

The PPC405 core accesses high-speed system resources through PLB interfaces on the instruction and data cache controllers. The PLB interfaces provide separate 32-bit address/64-bit data buses for the instruction and data sides.

The cache controllers are both PLB masters. PLB arbiters are implemented in the FPGA fabric and are available as soft IP cores.

Device Control Register (DCR) Bus Interface

The device control register (DCR) bus has 10 bits of address space for components external to the PPC405 core. Using the DCR bus to manage status and configuration registers reduces PLB traffic and improves system integrity. System resources on the DCR bus are protected or isolated from wayward code since the DCR bus is not part of the system memory map.

External Interrupt Controller (EIC) Interface

Two level-sensitive user interrupt pins (critical and non-critical) are available. They can be either driven by user defined logic or Xilinx soft interrupt controller IP core outside the Processor Block.

Clock/Power Management (CPM) Interface

The CPM interface supports several methods of clock distribution and power management. Three modes of operation that reduce power consumption below the normal operational level are available.

Reset Interface

There are three user reset input pins (core, chip, and system) and three user reset output pins for different levels of reset, if required.

Debug Interface

Debugging interfaces on the embedded PPC405 core, consisting of the JTAG and Trace ports, offer access to resources internal to the core and assist in software development. The JTAG port provides basic JTAG chip testing functionality as well as the ability for external debug tools to gain control of the processor for debug purposes. The Trace port furnishes programmers with a mechanism for acquiring instruction execution traces.

The JTAG port is compatible with IEEE Std 1149.1, which defines a test access port (TAP) and Boundary-Scan architecture. Extensions to the JTAG interface provide debuggers with processor control that includes stopping, starting, and stepping the PPC405 core. These extensions are compliant with the IEEE 1149.1 specifications for vendor-specific extensions.

- Execution unit
- Timers
- Debug logic unit

It operates on instructions in a five stage pipeline consisting of a fetch, decode, execute, write-back, and load write-back stage. Most instructions execute in a single cycle, including loads and stores.

Instruction and Data Cache

The embedded PPC405 core provides an instruction cache unit (ICU) and a data cache unit (DCU) that allow concurrent accesses and minimize pipeline stalls. The instruction and data cache array are 16 KB each. Both cache units are two-way set associative. Each way is organized into 256 lines of 32 bytes (eight words). The instruction set provides a rich assortment of cache control instructions, including instructions to read tag information and data arrays.

The PPC405 core accesses external memory through the instruction (ICU) and data cache units (DCU). The cache units each include a 64-bit PLB master interface, cache arrays, and a cache controller. The ICU and DCU handle cache misses as requests over the PLB to another PLB device such as an external bus interface unit. Cache hits are handled as single cycle memory accesses to the instruction and data caches.

Instruction Cache Unit (ICU)

The ICU provides one or two instructions per cycle to the instruction queue over a 64-bit bus. A line buffer (built into the output of the array for manufacturing test) enables the ICU to be accessed only once for every four instructions, to reduce power consumption by the array.

The ICU can forward any or all of the four or eight words of a line fill to the EXU to minimize pipeline stalls caused by cache misses. The ICU aborts speculative fetches abandoned by the EXU, eliminating unnecessary line fills and enabling the ICU to handle the next EXU fetch. Aborting abandoned requests also eliminates unnecessary external bus activity, thereby increasing external bus utilization.

Data Cache Unit (DCU)

The DCU transfers one, two, three, four, or eight bytes per cycle, depending on the number of byte enables presented by the CPU. The DCU contains a single-element command and store data queue to reduce pipeline stalls; this queue enables the DCU to independently process load/store and cache control instructions. Dynamic PLB request prioritization reduces pipeline stalls even further. When the DCU is busy with a low-priority request while a subsequent storage operation requested by the CPU is stalled; the DCU automatically increases the priority of the current request to the PLB.

The DCU provides additional features that allow the programmer to tailor its performance for a given application. The DCU can function in write-back or write-through mode,

as controlled by the Data Cache Write-through Register (DCWR) or the Translation Look-aside Buffer (TLB); the cache controller can be tuned for a balance of performance and memory coherency. Write-on-allocate, controlled by the store word on allocate (SWOA) field of the Core Configuration Register 0 (CCR0), can inhibit line fills caused by store misses, to further reduce potential pipeline stalls and unwanted external bus traffic.

Fetch and Decode Logic

The fetch/decode logic maintains a steady flow of instructions to the execution unit by placing up to two instructions in the fetch queue. The fetch queue consists of three buffers: pre-fetch buffer 1 (PFB1), pre-fetch buffer 0 (PFB0), and decode (DCD). The fetch logic ensures that instructions proceed directly to decode when the queue is empty.

Static branch prediction as implemented on the PPC405 core takes advantage of some standard statistical properties of code. Branches with negative address displacement are by default assumed taken. Branches that do not test the condition or count registers are also predicted as taken. The PPC405 core bases branch prediction upon these default conditions when a branch is not resolved and speculatively fetches along the predicted path. The default prediction can be overridden by software at assembly or compile time.

Branches are examined in the decode and pre-fetch buffer 0 fetch queue stages. Two branch instructions can be handled simultaneously. If the branch in decode is not taken, the fetch logic fetches along the predicted path of the branch instruction in pre-fetch buffer 0. If the branch in decode is taken, the fetch logic ignores the branch instruction in pre-fetch buffer 0.

Execution Unit

The embedded PPC405 core has a single issue execution unit (EXU) containing the register file, arithmetic logic unit (ALU), and the multiply-accumulate (MAC) unit. The execution unit performs all 32-bit PowerPC integer instructions in hardware.

The register file is comprised of thirty-two 32-bit general purpose registers (GPR), which are accessed with three read ports and two write ports. During the decode stage, data is read out of the GPRs and fed to the execution unit. Likewise, during the write-back stage, results are written to the GPR. The use of the five ports on the register file enables either a load or a store operation to execute in parallel with an ALU operation.

Memory Management Unit (MMU)

The embedded PPC405 core has a 4 GB address space, which is presented as a flat address space.

The MMU provides address translation, protection functions, and storage attribute control for embedded applications. The MMU supports demand-paged virtual memory and other management schemes that require precise control of logical-to-physical address mapping and flexible

Table 12: Summary of Voltage Supply Requirements for All Input and Output Standards

I/O Standard	V _{CCO}		V _{REF}	Termination Type	
	Output	Input	Input	Output	Input
LVTTTL ⁽¹⁾	3.3	3.3	N/R	N/R	N/R
LVC MOS33 ⁽¹⁾			N/R	N/R	N/R
LVDCI_33 ⁽¹⁾			N/R	Series	N/R
PCIX ⁽²⁾			N/R	N/R	N/R
PCI33_3 ⁽²⁾			N/R	N/R	N/R
PCI66_3 ⁽²⁾			N/R	N/R	N/R
LVDS_25	2.5	Note (3)	N/R	N/R	N/R
LVDSEXT_25			N/R	N/R	N/R
LDT_25			N/R	N/R	N/R
ULVDS_25			N/R	N/R	N/R
BLVDS_25			N/R	N/R	N/R
LVPECL_25			N/R	N/R	N/R
SSTL2_I			1.25	N/R	N/R
SSTL2_II			1.25	N/R	N/R
LVC MOS25		2.5	N/R	N/R	N/R
LVDCI_25			N/R	Series	N/R
LVDCI_DV2_25			N/R	Series	N/R
LVDS_25_DCI			N/R	N/R	Split
LVDSEXT_25_DCI			N/R	N/R	Split
SSTL2_I_DCI			1.25	N/R	Split
SSTL2_II_DCI			1.25	Split	Split
LVDS_25_DT			N/R	N/R	N/R
LVDSEXT_25_DT			N/R	N/R	N/R
LDT_25_DT			N/R	N/R	N/R
ULVDS_25_DT			N/R	N/R	N/R

Table 12: Summary of Voltage Supply Requirements for All Input and Output Standards (Continued)

I/O Standard	V _{CCO}		V _{REF}	Termination Type	
	Output	Input	Input	Output	Input
HSTL_III_18	1.8	Note (3)	1.1	N/R	N/R
HSTL_IV_18			1.1	N/R	N/R
HSTL_I_18			0.9	N/R	N/R
HSTL_II_18			0.9	N/R	N/R
SSTL18_I			0.9	N/R	N/R
SSTL18_II			0.9	N/R	N/R
LVC MOS18		1.8	N/R	N/R	N/R
LVDCI_18			N/R	Series	N/R
LVDCI_DV2_18			N/R	Series	N/R
HSTL_III_DCI_18			1.1	N/R	Single
HSTL_IV_DCI_18			1.1	Single	Single
HSTL_I_DCI_18			0.9	N/R	Split
HSTL_II_DCI_18			0.9	Split	Split
SSTL18_I_DCI			0.9	N/R	Split
SSTL18_II_DCI			0.9	Split	Split
HSTL_III	1.5	Note (3)	0.9	N/R	N/R
HSTL_IV			0.9	N/R	N/R
HSTL_I			0.75	N/R	N/R
HSTL_II			0.75	N/R	N/R
LVC MOS15		1.5	N/R	N/R	N/R
LVDCI_15			N/R	Series	N/R
LVDCI_DV2_15			N/R	Series	N/R
GTLP_DCI			1	Single	Single
HSTL_III_DCI			0.9	N/R	Single
HSTL_IV_DCI			0.9	Single	Single
HSTL_I_DCI			0.75	N/R	Split
HSTL_II_DCI			0.75	Split	Split
GTLP_DCI	1.2	1.2	0.8	Single	Single
GTLP	N/R	Note (3)	1	N/R	N/R
GTL			0.8	N/R	N/R

Notes:

1. See application note [XAPP659](#) for more detailed information.
2. See application note [XAPP653](#) for more detailed information.
3. Pin voltage must not exceed V_{CCO}.
4. N/R = no requirement.

Figure 30 provides examples illustrating the use of the LVDS_25_DCI and LVDSEXT_25_DCI I/O standards. For a complete list, see the [Virtex-II Pro Platform FPGA User Guide](#).

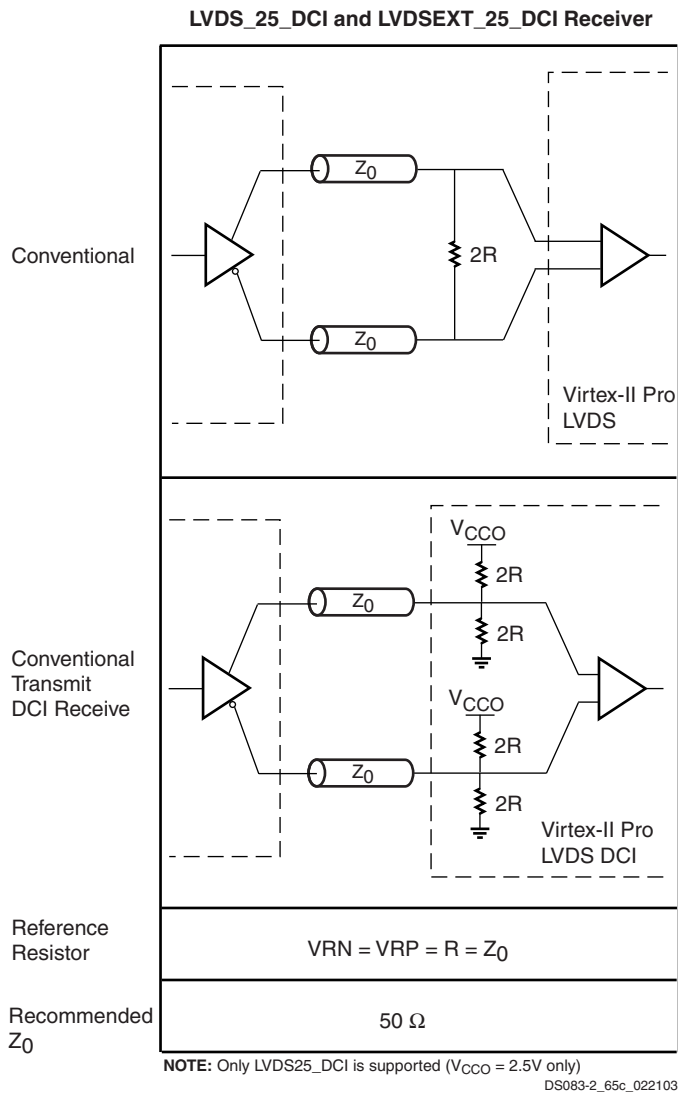


Figure 30: LVDS DCI Usage Examples

On-Chip Differential Termination

Virtex-II Pro provides a true $100\ \Omega$ differential termination (DT) across the input differential receiver terminals. The LVDS_25_DT, LVDSEXT_25_DT, LDT_25_DT, and ULVDS_25_DT standards support on-chip differential termination.

The on-chip input differential termination in Virtex-II Pro provides major advantages over the external resistor or the DCI termination solution:

- Eliminates the stub at the receiver completely and therefore greatly improve signal integrity
- Consumes less power than DCI termination
- Supports LDT (not supported by DCI termination)
- Frees up VRP/VRN pins

Figure 31 provides examples illustrating the use of the LVDS_25_DT, LVDSEXT_25_DT, LDT_25_DT, and ULVDS_25_DT I/O standards. For further details, refer to [Solution Record 17244](#). Also see the [Virtex-II Pro Platform FPGA User Guide](#) for more design information.

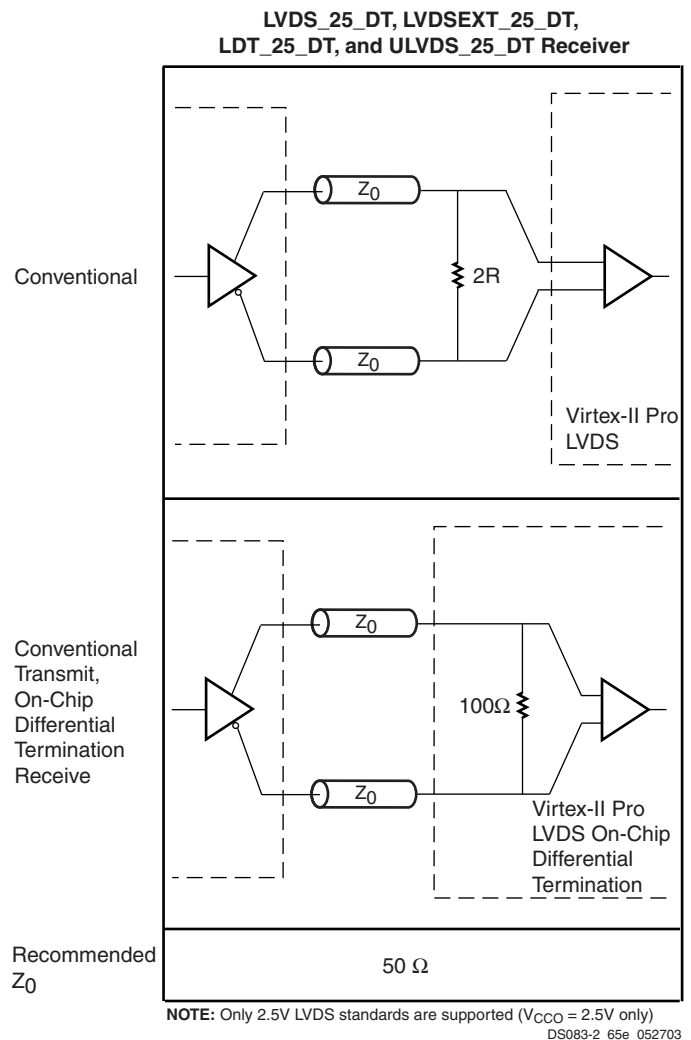


Figure 31: LVDS Differential Termination Usage Examples

Master SelectMAP Mode

This mode is a master version of the SelectMAP mode. The device is configured byte-wide on a CCLK supplied by the Virtex-II Pro FPGA device. Timing is similar to the Slave SelectMAP mode except that CCLK is supplied by the Virtex-II Pro FPGA.

Boundary-Scan (JTAG, IEEE 1532) Mode

In Boundary-Scan mode, dedicated pins are used for configuring the Virtex-II Pro device. The configuration is done entirely through the IEEE 1149.1 Test Access Port (TAP).

Virtex-II Pro device configuration using Boundary-Scan is compatible with with IEEE 1149.1-1993 standard and the new IEEE 1532 standard for In-System Configurable (ISC) devices. The IEEE 1532 standard is backward compliant with the IEEE 1149.1-1993 TAP and state machine. The IEEE Standard 1532 for In-System Configurable (ISC) devices is intended to be programmed, reprogrammed, or tested on the board via a physical and logical protocol. Configuration through the Boundary-Scan port is always available, independent of the mode selection. Selecting the Boundary-Scan mode simply turns off the other modes.

Table 32: Virtex-II Pro Configuration Mode Pin Settings

Configuration Mode ⁽¹⁾	M2	M1	M0	CCLK Direction	Data Width	Serial D _{OUT} ⁽²⁾
Master Serial	0	0	0	Out	1	Yes
Slave Serial	1	1	1	In	1	Yes
Master SelectMAP	0	1	1	Out	8	No
Slave SelectMAP	1	1	0	In	8	No
Boundary-Scan	1	0	1	N/A	1	No

Notes:

1. The HSWAP_EN pin controls the pull-ups. Setting M2, M1, and M0 selects the configuration mode, while the HSWAP_EN pin controls whether or not the pull-ups are used.
2. Daisy chaining is possible only in modes where Serial D_{OUT} is used. For example, in SelectMAP modes, the first device does NOT support daisy chaining of downstream devices.

Table 33 lists the default total number of bits required to configure each device.

Table 33: Virtex-II Pro Default Bitstream Lengths

Device	Number of Configuration Bits
XC2VP2	1,305,376
XC2VP4	3,006,496
XC2VP7	4,485,408
XC2VP20	8,214,560
XC2VPX20	8,214,560
XC2VP30	11,589,920
XC2VP40	15,868,192
XC2VP50	19,021,344
XC2VP70	26,098,976
XC2VPX70	26,098,976
XC2VP100	34,292,768

Configuration Sequence

The configuration of Virtex-II Pro devices is a three-phase process. First, the configuration memory is cleared. Next, configuration data is loaded into the memory, and finally, the logic is activated by a start-up process.

Configuration is automatically initiated on power-up unless it is delayed by the user. The INIT_B pin can be held Low using an open-drain driver. An open-drain is required since INIT_B is a bidirectional open-drain pin that is held Low by a Virtex-II Pro FPGA device while the configuration memory is being cleared. Extending the time that the pin is Low causes the configuration sequencer to wait. Thus, configuration is delayed by preventing entry into the phase where data is loaded.

The configuration process can also be initiated by asserting the PROG_B pin. The end of the memory-clearing phase is signaled by the INIT_B pin going High, and the completion of the entire process is signaled by the DONE pin going High. The Global Set/Reset (GSR) signal is pulsed after the last frame of configuration data is written but before the start-up sequence. The GSR signal resets all flip-flops on the device.

The default start-up sequence is that one CCLK cycle after DONE goes High, the global 3-state signal (GTS) is released. This permits device outputs to turn on as necessary. One CCLK cycle later, the Global Write Enable (GWE) signal is released. This permits the internal storage elements to begin changing state in response to the logic and the user clock.

The relative timing of these events can be changed via configuration options in software. In addition, the GTS and GWE events can be made dependent on the DONE pins of multiple devices all going High, forcing the devices to start

Table 24: RocketIO X Receiver Switching Characteristics⁽¹⁾

Description	Symbol	Conditions	Min	Typ	Max	Units
Receive total jitter tolerance using default equalization and PRBS-15 pattern	T_{JTOL}	2.488 Gb/s		0.80	0.65	UI ⁽²⁾
		3.125 Gb/s		0.80	0.65	UI
		4.25 Gb/s		0.80	0.65	UI
		6.25 Gb/s		0.80	0.65	UI
Receive random jitter tolerance	T_{RJTO}	2.488 Gb/s		0.30		UI
		3.125 Gb/s		0.30		UI
		4.25 Gb/s		0.30		UI
		6.25 Gb/s		0.30		UI
Receive sinusoidal jitter tolerance measured at 70 MHz	T_{SJTO}	2.488 Gb/s		0.30	0.15	UI
		3.125 Gb/s		0.30	0.15	UI
		4.25 Gb/s		0.30	0.15	UI
		6.25 Gb/s		0.30	0.15	UI
Receive deterministic jitter tolerance	T_{DJTO}	2.488 Gb/s		0.55	0.45	UI
		3.125 Gb/s		0.55	0.45	UI
		4.25 Gb/s		0.55	0.45	UI
		6.25 Gb/s		0.50	0.45	UI
Receive latency ⁽³⁾	T_{RXLAT}			25	34 ⁽⁴⁾	RXUSRCLK cycles
RXUSRCLK duty cycle	T_{RXDC}		45	50	55	%
RXUSRCLK2 duty cycle	T_{RX2DC}		45	50	55	%
Differential receive input sensitivity	V_{EYE}			120	250	mV

Notes:

1. The XC2VPX70 operates at a fixed 4.25 Gb/s baud rate.
2. UI = Unit Interval
3. Receive latency delay RXP/RXN to RXDATA. Refer to [RocketIO X Transceiver User Guide](#) for more information on calculating latency.
4. This maximum may occur when certain conditions are present and clock correction and channel bonding are enabled. If these functions are both disabled, the maximum will be near the typical values.

Table 6: FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	IO_L88N_7/VREF_7	L5			
7	IO_L86P_7	L6			
7	IO_L86N_7	K6			
7	IO_L85P_7	K1			
7	IO_L85N_7	K2			
7	IO_L60P_7	K3	NC		
7	IO_L60N_7	K4	NC		
7	IO_L58P_7	K5	NC		
7	IO_L58N_7/VREF_7	J5	NC		
7	IO_L56P_7	J1	NC		
7	IO_L56N_7	J2	NC		
7	IO_L55P_7	J3	NC		
7	IO_L55N_7	J4	NC		
7	IO_L54P_7	J6	NC		
7	IO_L54N_7	H5	NC		
7	IO_L52P_7	H1	NC		
7	IO_L52N_7/VREF_7	H2	NC		
7	IO_L50P_7	H3	NC		
7	IO_L50N_7	H4	NC		
7	IO_L49P_7	G1	NC		
7	IO_L49N_7	G2	NC		
7	IO_L48P_7	G3	NC		
7	IO_L48N_7	G4	NC		
7	IO_L46P_7	G5	NC		
7	IO_L46N_7/VREF_7	F5	NC		
7	IO_L43P_7	F1	NC		
7	IO_L43N_7	F2	NC		
7	IO_L06P_7	F3			
7	IO_L06N_7	F4			
7	IO_L04P_7	E1			
7	IO_L04N_7/VREF_7	E2			
7	IO_L03P_7	E3			
7	IO_L03N_7	E4			
7	IO_L02P_7	D1			
7	IO_L02N_7	D2			
7	IO_L01P_7/VRN_7	C1			
7	IO_L01N_7/VRP_7	C2			

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	VCCINT	U16			
N/A	VCCINT	U18			
N/A	VCCINT	V10			
N/A	VCCINT	V17			
N/A	VCCINT	V18			
N/A	VCCINT	W19			
N/A	VCCAUX	B2			
N/A	VCCAUX	N1			
N/A	VCCAUX	P1			
N/A	VCCAUX	A13			
N/A	VCCAUX	A14			
N/A	VCCAUX	AE2			
N/A	VCCAUX	B25			
N/A	VCCAUX	N26			
N/A	VCCAUX	P26			
N/A	VCCAUX	AE25			
N/A	VCCAUX	AF13			
N/A	VCCAUX	AF14			
N/A	GND	C3			
N/A	GND	D4			
N/A	GND	E5			
N/A	GND	F6			
N/A	GND	G7			
N/A	GND	Y7			
N/A	GND	AA6			
N/A	GND	AB5			
N/A	GND	AC4			
N/A	GND	AD3			
N/A	GND	C24			
N/A	GND	D23			
N/A	GND	E22			
N/A	GND	F21			
N/A	GND	G20			
N/A	GND	K10			
N/A	GND	K12			
N/A	GND	K13			
N/A	GND	K14			

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
0	IO_L01N_0/VRP_0		E25			
0	IO_L01P_0/VRN_0		E24			
0	IO_L02N_0		F24			
0	IO_L02P_0		F23			
0	IO_L03N_0		E23			
0	IO_L03P_0/VREF_0		E22			
0	IO_L05_0/No_Pair		G23			
0	IO_L06N_0		H22			
0	IO_L06P_0		G22			
0	IO_L07N_0		F22			
0	IO_L07P_0		F21			
0	IO_L08N_0		D24			
0	IO_L08P_0		C24			
0	IO_L09N_0		H21			
0	IO_L09P_0/VREF_0		G21			
0	IO_L37N_0		E21			
0	IO_L37P_0		D21			
0	IO_L38N_0		D23			
0	IO_L38P_0		C23			
0	IO_L39N_0		H20			
0	IO_L39P_0		G20			
0	IO_L43N_0		E20			
0	IO_L43P_0		D20			
0	IO_L44N_0		B23			
0	IO_L44P_0		A23			
0	IO_L45N_0		H19			
0	IO_L45P_0/VREF_0		G19			
0	IO_L46N_0		E19	NC		
0	IO_L46P_0		E18	NC		
0	IO_L47N_0		C22	NC		
0	IO_L47P_0		B22	NC		
0	IO_L48N_0		F20	NC		
0	IO_L48P_0		F19	NC		
0	IO_L49N_0		G17	NC		
0	IO_L49P_0		F17	NC		
0	IO_L50_0/No_Pair		B21	NC		

Table 9: FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
7	IO_L36N_7		F27	NC		
7	IO_L35P_7		K24	NC		
7	IO_L35N_7		K23	NC		
7	IO_L34P_7		E30	NC		
7	IO_L34N_7/VREF_7		E29	NC		
7	IO_L33P_7		E28	NC		
7	IO_L33N_7		E27	NC		
7	IO_L32P_7		H26	NC		
7	IO_L32N_7		H25	NC		
7	IO_L31P_7		D30	NC		
7	IO_L31N_7		D29	NC		
7	IO_L06P_7		D28			
7	IO_L06N_7		C27			
7	IO_L05P_7		J24			
7	IO_L05N_7		J23			
7	IO_L04P_7		C30			
7	IO_L04N_7/VREF_7		C29			
7	IO_L03P_7		D26			
7	IO_L03N_7		C26			
7	IO_L02P_7		G26			
7	IO_L02N_7		G25			
7	IO_L01P_7/VRN_7		B28			
7	IO_L01N_7/VRP_7		A28			
0	VCCO_0		K21			
0	VCCO_0		K20			
0	VCCO_0		K19			
0	VCCO_0		K18			
0	VCCO_0		K17			
0	VCCO_0		K16			
0	VCCO_0		J21			
0	VCCO_0		J20			
0	VCCO_0		J19			
0	VCCO_0		J18			
1	VCCO_1		K15			
1	VCCO_1		K14			

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
N/A	GND	AP19		
N/A	GND	AK19		
N/A	GND	AF19		
N/A	GND	AA19		
N/A	GND	Y19		
N/A	GND	W19		
N/A	GND	V19		
N/A	GND	U19		
N/A	GND	T19		
N/A	GND	R19		
N/A	GND	P19		
N/A	GND	J19		
N/A	GND	E19		
N/A	GND	A19		
N/A	GND	AP18		
N/A	GND	AA18		
N/A	GND	Y18		
N/A	GND	W18		
N/A	GND	V18		
N/A	GND	U18		
N/A	GND	T18		
N/A	GND	R18		
N/A	GND	P18		
N/A	GND	A18		
N/A	GND	AA17		
N/A	GND	Y17		
N/A	GND	W17		
N/A	GND	V17		
N/A	GND	U17		
N/A	GND	T17		
N/A	GND	R17		
N/A	GND	P17		
N/A	GND	AP16		
N/A	GND	AK16		
N/A	GND	AF16		
N/A	GND	AA16		
N/A	GND	Y16		
N/A	GND	W16		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
2	IO_L49N_2	U5		
2	IO_L49P_2	U6		
2	IO_L50N_2	U13		
2	IO_L50P_2	V13		
2	IO_L51N_2	U4		
2	IO_L51P_2	T4		
2	IO_L52N_2/VREF_2	U1		
2	IO_L52P_2	U2		
2	IO_L53N_2	V9		
2	IO_L53P_2	V10		
2	IO_L54N_2	V7		
2	IO_L54P_2	V8		
2	IO_L55N_2	V5		
2	IO_L55P_2	V6		
2	IO_L56N_2	V11		
2	IO_L56P_2	V12		
2	IO_L57N_2	V3		
2	IO_L57P_2	V4		
2	IO_L58N_2/VREF_2	V1		
2	IO_L58P_2	V2		
2	IO_L59N_2	W10		
2	IO_L59P_2	W11		
2	IO_L60N_2	W7		
2	IO_L60P_2	W8		
2	IO_L85N_2	W5		
2	IO_L85P_2	W6		
2	IO_L86N_2	W12		
2	IO_L86P_2	W13		
2	IO_L87N_2	W3		
2	IO_L87P_2	W4		
2	IO_L88N_2/VREF_2	Y7		
2	IO_L88P_2	Y8		
2	IO_L89N_2	W9		
2	IO_L89P_2	Y9		
2	IO_L90N_2	Y3		
2	IO_L90P_2	Y4		
3	IO_L90N_3	AA7		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
2	VCCO_2	F8		
2	VCCO_2	U7		
2	VCCO_2	Y5		
2	VCCO_2	N4		
2	VCCO_2	J4		
2	VCCO_2	E4		
2	VCCO_2	U3		
2	VCCO_2	E1		
1	VCCO_1	N14		
1	VCCO_1	K13		
1	VCCO_1	F13		
1	VCCO_1	P19		
1	VCCO_1	P18		
1	VCCO_1	P17		
1	VCCO_1	K17		
1	VCCO_1	F17		
1	VCCO_1	P16		
1	VCCO_1	N16		
1	VCCO_1	P15		
1	VCCO_1	N15		
0	VCCO_0	K27		
0	VCCO_0	F27		
0	VCCO_0	N26		
0	VCCO_0	P25		
0	VCCO_0	N25		
0	VCCO_0	P24		
0	VCCO_0	N24		
0	VCCO_0	P23		
0	VCCO_0	K23		
0	VCCO_0	F23		
0	VCCO_0	P22		
0	VCCO_0	P21		
N/A	CCLK	AJ10		
N/A	PROG_B	D32		
N/A	DONE	AJ11		
N/A	M0	AP31		
N/A	M1	AJ30		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	GND A18	AU16		
N/A	TXPPAD18	AW18		
N/A	TXNPAD18	AW19		
N/A	VTTXPAD18	AV19		
N/A	AVCCAUXTX18	AV18		
N/A	AVCCAUXRX19	AV21		
N/A	VTRXPAD19	AV22		
N/A	RXNPAD19	AW21		
N/A	RXPPAD19	AW22		
N/A	GND A19	AU24		
N/A	TXPPAD19	AW23		
N/A	TXNPAD19	AW24		
N/A	VTTXPAD19	AV24		
N/A	AVCCAUXTX19	AV23		
N/A	AVCCAUXRX20	AV25		
N/A	VTRXPAD20	AV26		
N/A	RXNPAD20	AW25		
N/A	RXPPAD20	AW26		
N/A	GND A20	AU27		
N/A	TXPPAD20	AW27		
N/A	TXNPAD20	AW28		
N/A	VTTXPAD20	AV28		
N/A	AVCCAUXTX20	AV27		
N/A	AVCCAUXRX21	AV29		
N/A	VTRXPAD21	AV30		
N/A	RXNPAD21	AW29		
N/A	RXPPAD21	AW30		
N/A	GND A21	AU31		
N/A	TXPPAD21	AW31		
N/A	TXNPAD21	AW32		
N/A	VTTXPAD21	AV32		
N/A	AVCCAUXTX21	AV31		
N/A	AVCCAUXRX23	AV33		
N/A	VTRXPAD23	AV34		
N/A	RXNPAD23	AW33		
N/A	RXPPAD23	AW34		
N/A	GND A23	AU34		
N/A	TXPPAD23	AW35		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	GND		AB18		
N/A	GND		AB17		
N/A	GND		AB11		
N/A	GND		AB8		
N/A	GND		AB5		
N/A	GND		AC41		
N/A	GND		AC26		
N/A	GND		AC25		
N/A	GND		AC24		
N/A	GND		AC23		
N/A	GND		AC22		
N/A	GND		AC21		
N/A	GND		AC20		
N/A	GND		AC19		
N/A	GND		AC18		
N/A	GND		AC17		
N/A	GND		AC2		
N/A	GND		AD26		
N/A	GND		AD25		
N/A	GND		AD24		
N/A	GND		AD23		
N/A	GND		AD22		
N/A	GND		AD21		
N/A	GND		AD20		
N/A	GND		AD19		
N/A	GND		AD18		
N/A	GND		AD17		
N/A	GND		AE37		
N/A	GND		AE34		
N/A	GND		AE26		
N/A	GND		AE25		
N/A	GND		AE24		
N/A	GND		AE23		
N/A	GND		AE22		
N/A	GND		AE21		
N/A	GND		AE20		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
3	IO_L56N_3	AC11	
3	IO_L56P_3	AC12	
3	IO_L55N_3	AD3	
3	IO_L55P_3	AE3	
3	IO_L54N_3	AE1	
3	IO_L54P_3	AE2	
3	IO_L53N_3	AC6	
3	IO_L53P_3	AC7	
3	IO_L52N_3	AF2	
3	IO_L52P_3	AF3	
3	IO_L51N_3/VREF_3	AF6	
3	IO_L51P_3	AG6	
3	IO_L50N_3	AD10	
3	IO_L50P_3	AD11	
3	IO_L49N_3	AG4	
3	IO_L49P_3	AG5	
3	IO_L48N_3	AF4	
3	IO_L48P_3	AG3	
3	IO_L47N_3	AC10	
3	IO_L47P_3	AD9	
3	IO_L46N_3	AG1	
3	IO_L46P_3	AG2	
3	IO_L45N_3/VREF_3	AG7	
3	IO_L45P_3	AH7	
3	IO_L44N_3	AC8	
3	IO_L44P_3	AD7	
3	IO_L43N_3	AH4	
3	IO_L43P_3	AH5	
3	IO_L42N_3	AH1	
3	IO_L42P_3	AH2	
3	IO_L41N_3	AE10	
3	IO_L41P_3	AE11	
3	IO_L40N_3	AJ6	
3	IO_L40P_3	AJ7	
3	IO_L39N_3/VREF_3	AH6	
3	IO_L39P_3	AJ5	
3	IO_L38N_3	AE8	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
5	IO_L10N_5	AW27	NC
5	IO_L10P_5	AW26	NC
5	IO_L45N_5/VREF_5	AN27	
5	IO_L45P_5	AP27	
5	IO_L44N_5	AU27	
5	IO_L44P_5	AV27	
5	IO_L43N_5	AR27	
5	IO_L43P_5	AR26	
5	IO_L39N_5	AL27	
5	IO_L39P_5	AM27	
5	IO_L38N_5	BA28	
5	IO_L38P_5	BB28	
5	IO_L37N_5	AY28	
5	IO_L37P_5	AY27	
5	IO_L87N_5/VREF_5	AN28	
5	IO_L87P_5	AP28	
5	IO_L86N_5	AU28	
5	IO_L86P_5	AV28	
5	IO_L85N_5	AT28	
5	IO_L85P_5	AT27	
5	IO_L84N_5	AL28	
5	IO_L84P_5	AM28	
5	IO_L83_5/No_Pair	BA29	
5	IO_L80_5/No_Pair	BB29	
5	IO_L79N_5	AY29	
5	IO_L79P_5	AW28	
5	IO_L78N_5	AN29	
5	IO_L78P_5	AP29	
5	IO_L77N_5	AU29	
5	IO_L77P_5	AV29	
5	IO_L76N_5	AT29	
5	IO_L76P_5	AR28	
5	IO_L36N_5/VREF_5	AL29	
5	IO_L36P_5	AM29	
5	IO_L35N_5	AY30	
5	IO_L35P_5	BA30	
5	IO_L34N_5	AT30	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
7	IO_L08N_7	N35	
7	IO_L07P_7	G41	
7	IO_L07N_7	G42	
7	IO_L72P_7	G39	
7	IO_L72N_7	G40	
7	IO_L71P_7	P32	
7	IO_L71N_7	P33	
7	IO_L70P_7	F38	
7	IO_L70N_7/VREF_7	G38	
7	IO_L69P_7	F37	
7	IO_L69N_7	G37	
7	IO_L68P_7	N32	
7	IO_L68N_7	N33	
7	IO_L67P_7	G35	
7	IO_L67N_7	G36	
7	IO_L66P_7	F41	
7	IO_L66N_7	F42	
7	IO_L65P_7	P31	
7	IO_L65N_7	N31	
7	IO_L64P_7	E41	
7	IO_L64N_7/VREF_7	F40	
7	IO_L63P_7	E36	
7	IO_L63N_7	F36	
7	IO_L62P_7	M34	
7	IO_L62N_7	M35	
7	IO_L61P_7	E35	
7	IO_L61N_7	F35	
7	IO_L84P_7	D40	
7	IO_L84N_7	E40	
7	IO_L83P_7	L34	
7	IO_L83N_7	L35	
7	IO_L82P_7	D39	
7	IO_L82N_7/VREF_7	E39	
7	IO_L81P_7	D38	
7	IO_L81N_7	E37	
7	IO_L80P_7	K34	
7	IO_L80N_7	J35	

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
2	VCCO_2	F4	
1	VCCO_1	R21	
1	VCCO_1	P21	
1	VCCO_1	R20	
1	VCCO_1	P20	
1	VCCO_1	R19	
1	VCCO_1	P19	
1	VCCO_1	R18	
1	VCCO_1	P18	
1	VCCO_1	H18	
1	VCCO_1	D18	
1	VCCO_1	P17	
1	VCCO_1	H14	
1	VCCO_1	D14	
1	VCCO_1	M13	
1	VCCO_1	D10	
0	VCCO_0	D33	
0	VCCO_0	M30	
0	VCCO_0	H29	
0	VCCO_0	D29	
0	VCCO_0	P26	
0	VCCO_0	R25	
0	VCCO_0	P25	
0	VCCO_0	H25	
0	VCCO_0	D25	
0	VCCO_0	R24	
0	VCCO_0	P24	
0	VCCO_0	R23	
0	VCCO_0	P23	
0	VCCO_0	R22	
0	VCCO_0	P22	
N/A	CCLK	AM10	
N/A	PROG_B	J33	
N/A	DONE	AN10	
N/A	M0	AP33	
N/A	M1	AN33	